



Product Specification

Product Name: **M904S**
Bluetooth SiP Module
-BT 4.0 LE

Version: **1.04**

Doc No:

Date: **Nov 25th, 2016**

Document History

| Date | Revise Contents | Revise by | Version |
|---------------|--|-------------|---------|
| Jan. 23, 2014 | Initial Version | Brian Juang | XA |
| Apr. 28, 2015 | | | 1.01 |
| Dec. 29, 2015 | | | 1.02 |
| Jun. 14, 2016 | Add the antenna Design guide, and Modify Power consumption | PJ Chang | 1.03 |
| Nov. 25, 2016 | 1. Revise the reference scheme 2. Add FCC Related information | PJ Chang | 1.04 |

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1 Description

The SiP module M904S is a small size module with conformal shielding. The module provides full function of Bluetooth 4.0 Low Energy in a tiny module via 48 pins LGA Foot Print. The M904S module provides everything required to create Bluetooth 4.0 Low Energy product with RF, baseband, MCU, qualified Bluetooth v4.0 stack and customer application running on a single IC.

M904S enables ultra-low power connectivity and basic data transfer for applications previously limited by the power consumption, size constraints and complexity of other wireless standards. The low power consumption and excellent radio performance make it the best solution for OEM /ODM customers who require embedded Bluetooth 4.0 Low Energy feature, such as, IP camera, car key, sport and fitness watch, mouse, led light bulb etc.

For the software and driver development, we provide extensive technical document and reference software code for the system integration.

Hardware evaluation kit and development utilities will be released base on listed OS and processors to OEM customers.

2 Feature

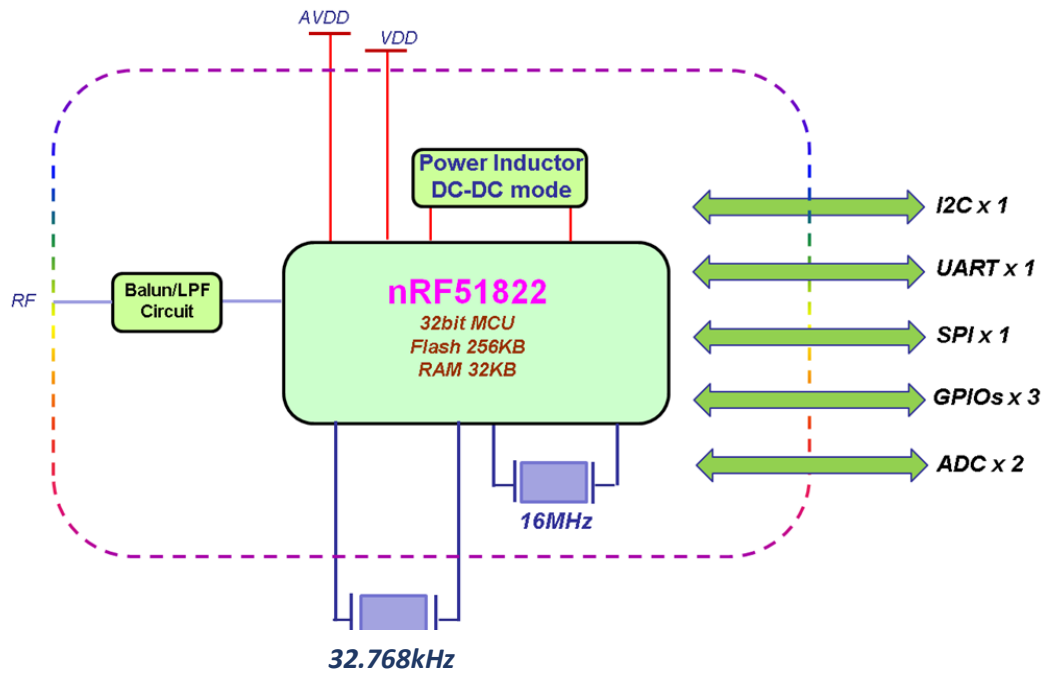
- Bluetooth® v4.0 LE radio technology
- -90 dBm sensitivity in Bluetooth® low energy mode
- 250 kbps, 1 Mbps, 2 Mbps supported data rates
- TX Power -20 to +4 dBm in 4 dB steps
- TX Power -30 dBm Whisper mode
- 12 mA peak RX, 10 mA peak TX (0 dBm)
- 256 kB embedded flash program memory
- Supply voltage range 1.8 V to 3.6 V
- SPI Master/Slave
- Low power comparator
- Temperature sensor
- Two-wire Master (I2C compatible)
- UART (CTS/RTS)
- AES HW encryption
- Real Timer Counter (RTC)
- Demo SW Open source on nRF51SDK v8/SoftDevice version 1
- Supports the nRF51SDK v11/SoftDevice v2
- LGA-48 package, 6.5 x 6.5 mm

ORDRING INFORMATION

| Part Number | Description |
|-------------|--|
| M904S | CLASS 2 Bluetooth single mode Module according BT-4.0. Bluetooth SMART |

3 Block Diagram

M904S supports UART command line interface to connect to the host processor. The simplified block diagram is depicted in the Fig. as below..



4 Technical Specification

4.1 Recommendable Operation Condition

Temperature, humidity

The M904S module has to withstand the operational requirements as listed in the table below

| No | Description | | Value | Unit |
|---|-------------------------------------|--|-------------|------|
| Ratings Over Operating Free-Air Temperature Range | | | | |
| 1 | Supply voltage | All supply pins must have the same voltage | −0.3 to 3.9 | V |
| 2 | Voltage on any digital pin | | TBD | V |
| 3 | Operating ambient temperature range | | −25 to 75 | °C |
| 4 | Storage temperature range | | −35 to 75 | °C |
| 5 | Bluetooth RF output | | 4 ± 1 | dBm |

4.2 Voltage

Power supply for the M904S module will be provided by the host via the power pins

| Operating Condition | Min. | Typ. | Max. |
|-------------------------------|------|------|------|
| DVDD_3V3 | 1.8 | 3.3 | 3.6 |
| I/O supply voltage (VDD_PADS) | 1.2 | 3.3 | 3.6 |

4.3 Wireless Specifications

The M904S module compliance with the following features and standards

| Features | Description |
|---------------------|--------------------------------------|
| Bluetooth Standards | Bluetooth core v4.0 Low Energy |
| Antenna Port | Support Single Antenna for Bluetooth |
| Frequency Band | 2.402 – 2.480 GHz |

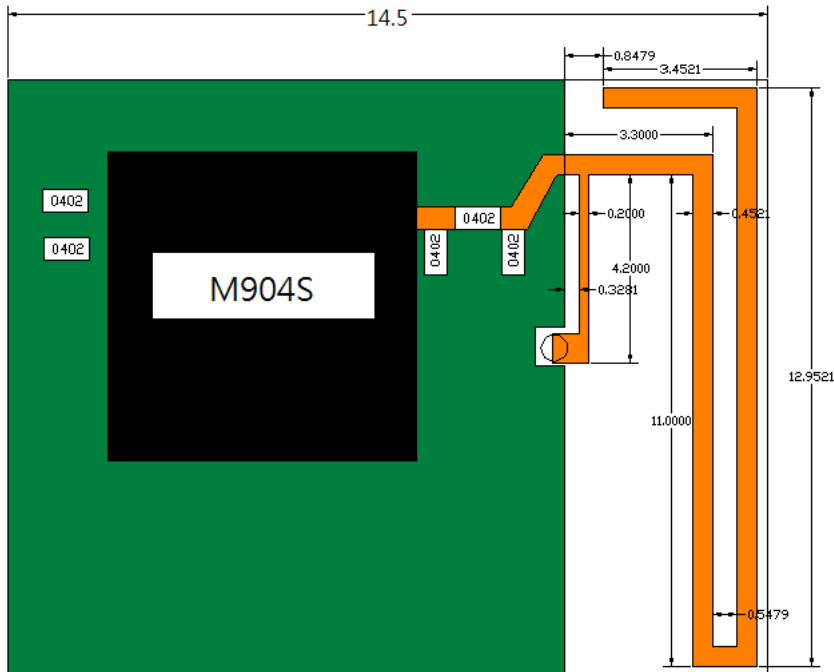
4.4 Radio Specifications Bluetooth 4.0 Low Energy

| Features | Description |
|-----------------------------------|-------------------------------------|
| Frequency Band | 2.402– 2.480 GHz (2.4 GHz ISM Band) |
| Number of selectable Sub channels | 40 channels |
| Modulation | GFSK |
| Supported rates | <2Mbps |
| Maximum receive level | -10dBm (with PER <30. 8%) |

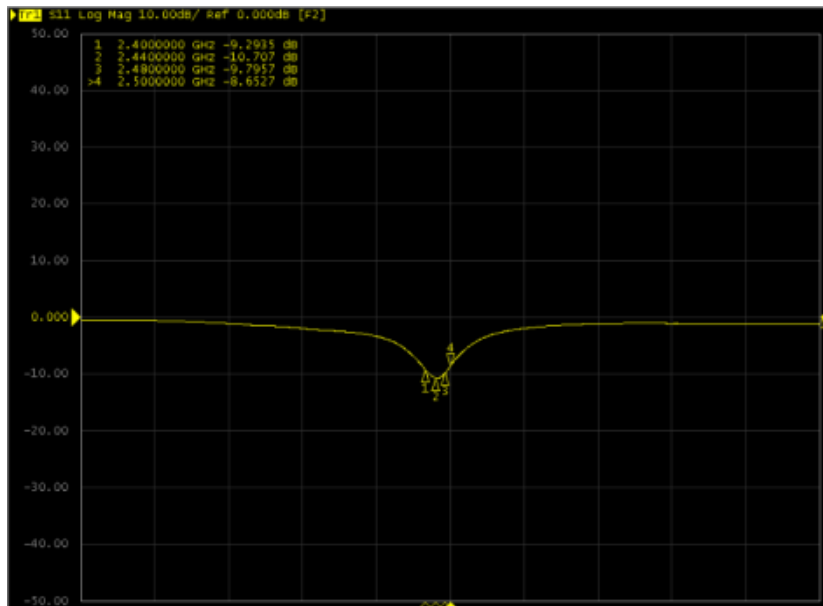
| Parameter | Mode and Conditions | Min. | Typ. | Max. | Unit. |
|-----------------------------------|---------------------|------|------|------|-------|
| RX sensitivity | | - | -90 | - | dBm |
| Maximum input | | | - | -10 | dBm |
| Frequency range | | 2400 | - | 2483 | MHz |
| Output power adjustment ranger | | -20 | - | 4 | dBm |
| Output power | | - | 2 | - | dBm |
| Output power variation | | - | 4 | - | dB |

4.5 External Antenna Design Guide

4.5.1 PCB Antenna Design Guide: Peak Gain: -2dBi Typ. / Avg. Gain: -3.5dBi Typ. (XZ-V)

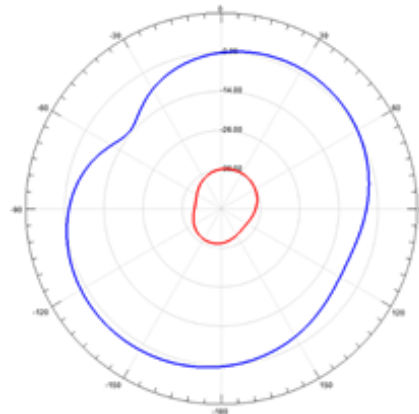
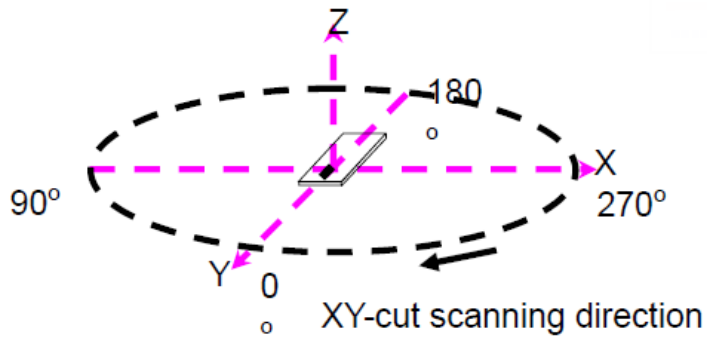


Return Loss

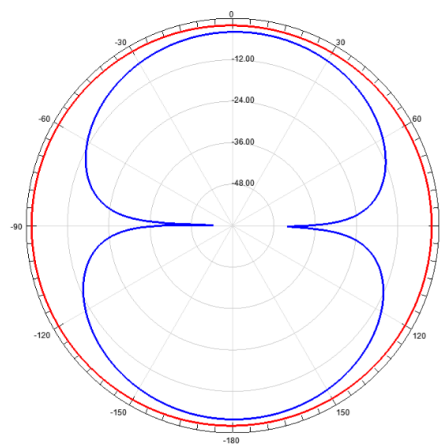
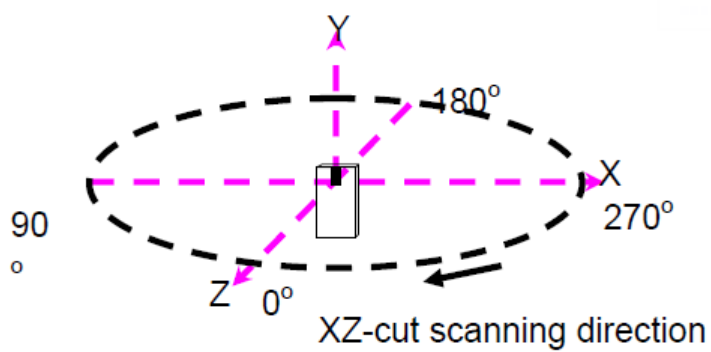


Radiation Patterns

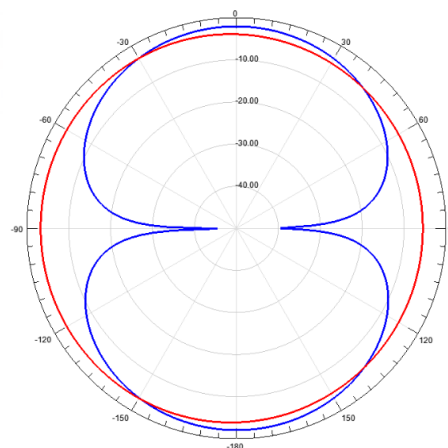
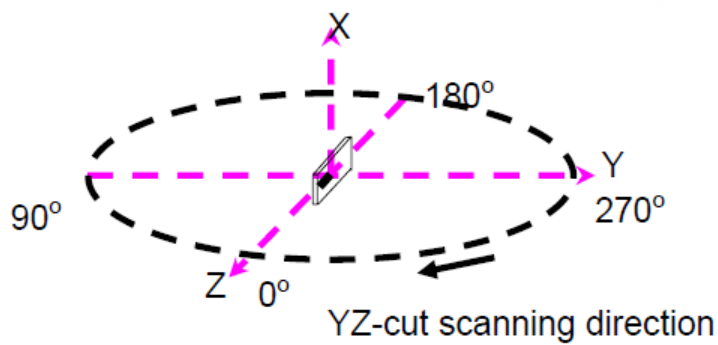
XY-V/XY-H



XZ-V/XZ-H



YZ-V/YZ-H



4.5.2 Chip Antenna Design Guide



AT3216 Series Multilayer Chip Antenna

Features

- ❖ Monolithic SMD with small, low-profile and light-weight type.
- ❖ Wide bandwidth

Applications

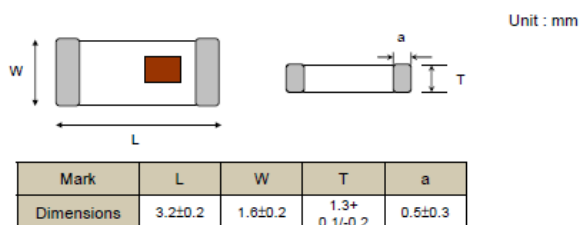
- ❖ Bluetooth/Wireless LAN/Home RF
- ❖ ISM band 2.4GHz applications



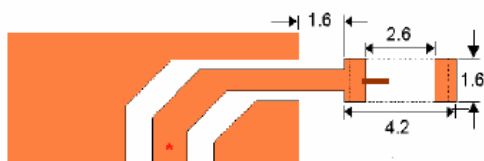
Specifications

| Part Number | Frequency Range (MHz) | Peak Gain (XZ-V) | Average Gain (XZ-V) | VSWR | Impedance |
|-----------------|-----------------------|------------------|---------------------|--------|-------------|
| AT3216-B2R7HAA_ | 2400 ~ 2500 | 0.5 dBi typ. | -0.5 dBi typ. | 2 max. | 50 Ω |

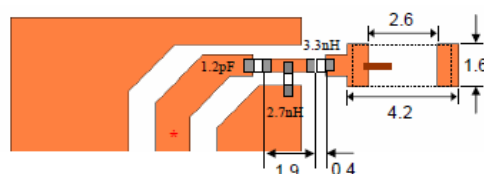
Dimensions and Recommended PC Board Pattern



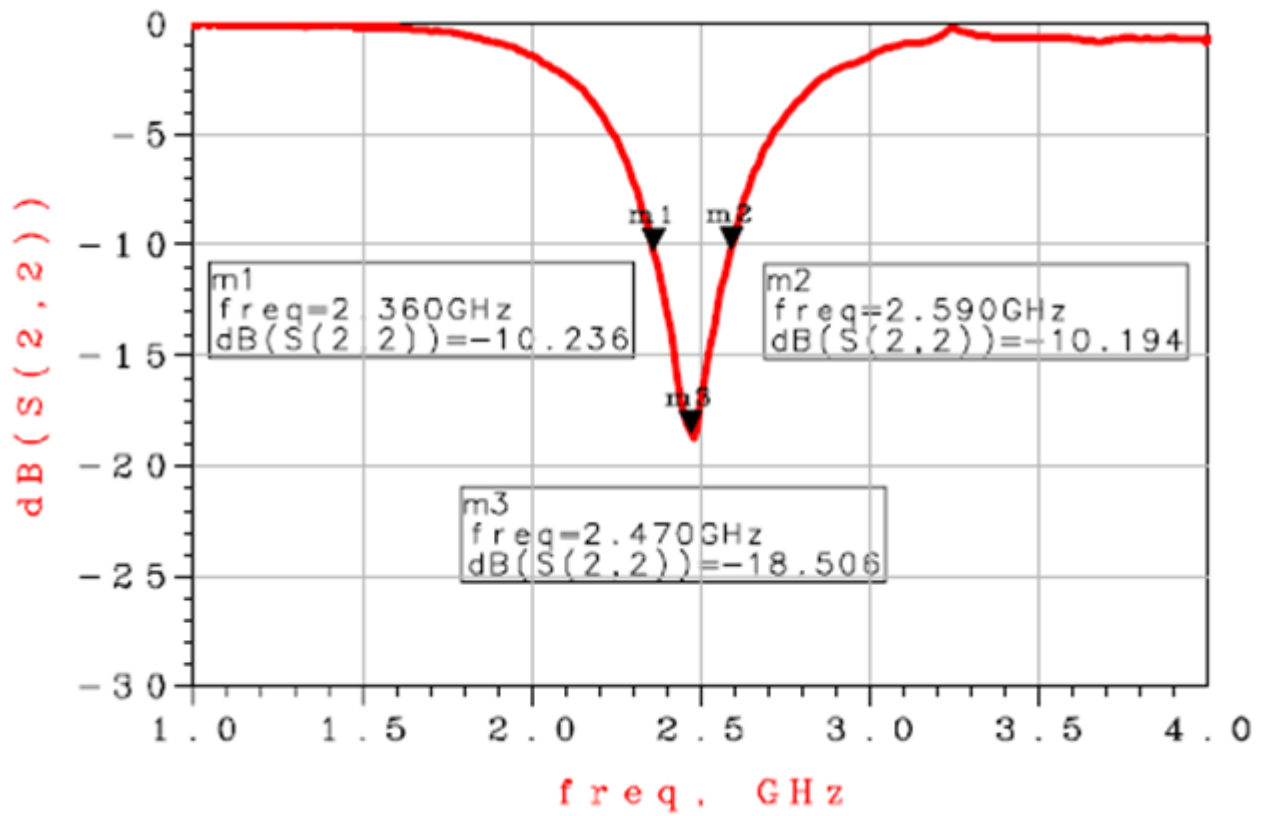
(a) Without Matching Circuits



(b) With Matching Circuits

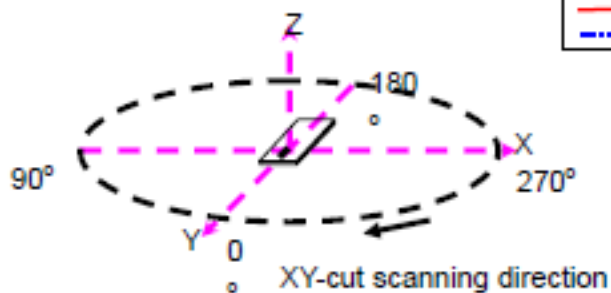


Return Loss\With Matching Circuits

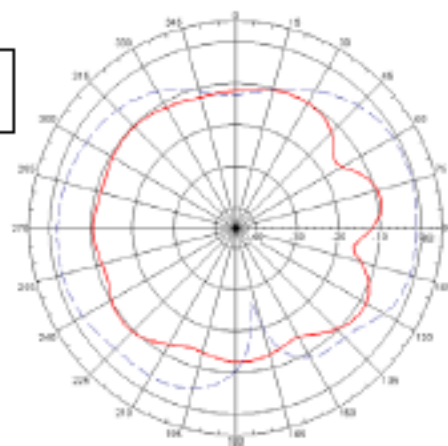


Radiation Patterns

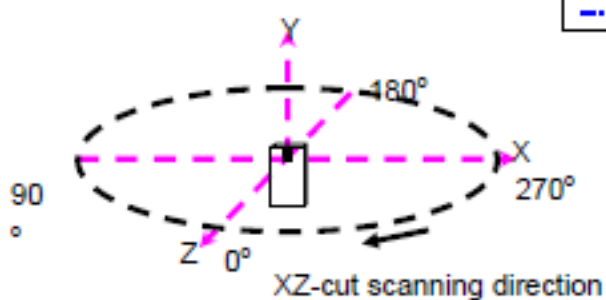
XY-V/XY-H



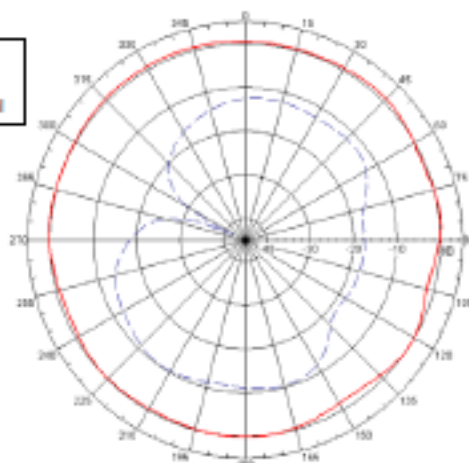
XY cut @2.45GHz
— Vertical
- - - Horizontal



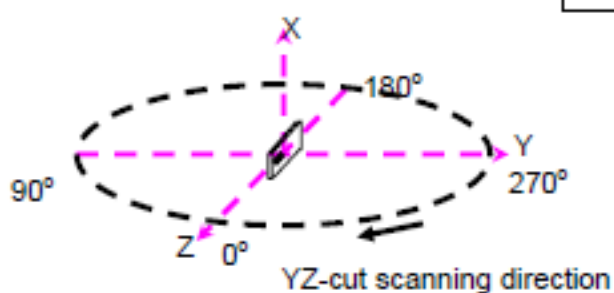
XZ-V/XZ-H



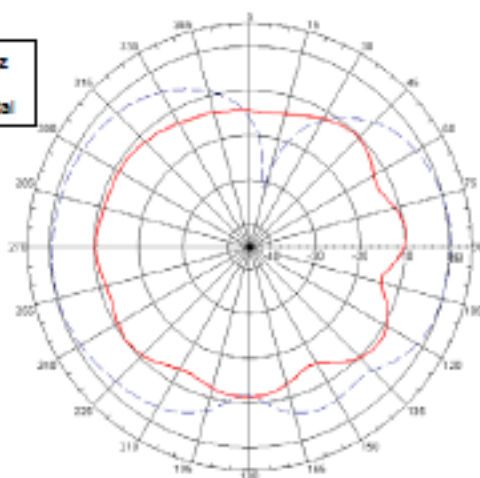
XZ cut @2.45GHz
— Vertical
- - - Horizontal



YZ-V/YZ-H



YZ cut @2.45GHz
— Vertical
- - - Horizontal



4.6 Power Consumption

| Item | Condition | Typ. |
|-------------------------------|------------|---------|
| Tx mode | 3.3V | 9.76mA |
| Rx mode | 3.3V | 12.15mA |
| System ON Constant Latency | Sleep Mode | 0.41uA |

Power Management

| Symbol | Description | Note | Min. | Typ. | Max. | Units | Test level |
|--------------------|--|--------------------------|------|------------------|------|---------|------------|
| I_{OFF} | Current in SYSTEM OFF, no RAM retention. | | | 0.6 ¹ | | μA | 2 |
| $I_{OFF, RET, 8k}$ | Additional current in SYSTEM OFF per retained RAM block (8 kB) | | | 0.6 ¹ | | μA | 2 |
| I_{OFF2ON} | OFF to CPU execute transition current. | | | 400 | | μA | 1 |
| t_{OFF2ON} | OFF to CPU execute. | | | 9.6 | 10.6 | μs | 1 |
| $I_{ON, 16k}$ | SYSTEM-ON base current with 16 kB RAM enabled. | | | 2.6 ¹ | | μA | 2 |
| $I_{ON, 32k}$ | SYSTEM-ON base current with 32 kB RAM enabled. | | | 3.8 ¹ | | μA | 2 |
| t_{1V2} | Startup time for 1V2 regulator. | | | 2.3 | | μs | 1 |
| $I_{1V2XO16}$ | Current drawn by 1V2 regulator and 16 MHz XO SC when both are on at the same time. | See Table 33 on page 48. | | 810 ² | | μA | 1 |

| Symbol | Description | Note | Min. | Typ. | Max. | Units | Test level |
|------------|--|------|-------------------|------|------------------|---------|------------|
| t_{1V7} | Startup time for 1V7 regulator | | | 2 | 3.6 | μs | 1 |
| I_{1V7} | Current drawn by 1V7 regulator | | | 105 | | μA | 2 |
| F_{DCDC} | DC/DC converter current conversion factor. | | 0.65 ⁴ | | 1.2 ⁴ | | 1 |

F_{DCDC} will vary depending on VDD and internal radio current consumption (I_{DD}). Please refer to the *nRF51 Series Reference Manual*, v3.0 or later, for a method to calculate $I_{DD, DCDC}$. See **Figure 11** on page 50 for a DC/DC conversion factor chart.

Radio Current Consumption

| Symbol | Description | Note | Min. | Typ. | Max. | Units | Test level |
|-----------------|---|------|------|------|------|-------|------------|
| $I_{TX,+4dBm}$ | TX only run current at $P_{OUT} = +4$ dBm. | 1 | | 16 | | mA | 4 |
| $I_{TX,0dBm}$ | TX only run current at $P_{OUT} = 0$ dBm. | 1 | | 10.5 | | mA | 4 |
| $I_{TX,-4dBm}$ | TX only run current at $P_{OUT} = -4$ dBm. | 1 | | 8 | | mA | 2 |
| $I_{TX,-8dBm}$ | TX only run current at $P_{OUT} = -8$ dBm. | 1 | | 7 | | mA | 2 |
| $I_{TX,-12dBm}$ | TX only run current at $P_{OUT} = -12$ dBm. | 1 | | 6.5 | | mA | 2 |
| $I_{TX,-16dBm}$ | TX only run current at $P_{OUT} = -16$ dBm. | 1 | | 6 | | mA | 2 |
| $I_{TX,-20dBm}$ | TX only run current at $P_{OUT} = -20$ dBm. | 1 | | 5.5 | | mA | 2 |
| $I_{TX,-30dBm}$ | TX only run current at $P_{OUT} = -30$ dBm. | 1 | | 5.5 | | mA | 2 |
| $I_{START,TX}$ | TX startup current. | 2 | | 7 | | mA | 1 |
| $I_{RX,250}$ | RX only run current at 250 kbps. | | | 12.6 | | mA | 1 |
| $I_{RX,1M}$ | RX only run current at 1 Mbps. | | | 13 | | mA | 4 |
| $I_{RX,2M}$ | RX only run current at 2 Mbps. | | | 13.4 | | mA | 1 |
| $I_{START,RX}$ | RX startup current. | 3 | | 8.7 | | mA | 1 |

1. Valid for data rates 250 kbps, 1 Mbps, and 2 Mbps.
2. Average current consumption (at 0 dBm TX output power) for TX startup (130 μ s), and when changing mode from RX to TX (130 μ s).
3. Average current consumption for RX startup (130 μ s), and when changing mode from TX to RX (130 μ s).

Transmitter Specifications

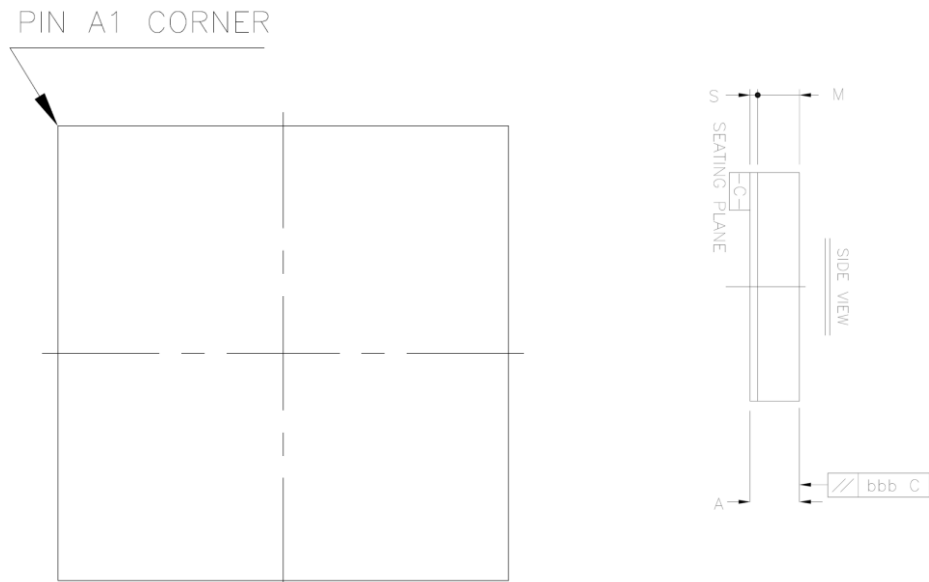
| Symbol | Description | Min. | Typ. | Max. | Units | Test level |
|---------------|---|------|------|---------|-------|------------|
| P_{RF} | Maximum output power. | | 4 | | dBm | 4 |
| P_{RFC} | RF power control range. | 20 | 24 | | dB | 2 |
| PRFCR | RF power accuracy. | | | ± 4 | dB | 1 |
| P_{WHISP} | RF power whisper mode. | | -30 | | dBm | 2 |
| P_{BW2} | 20 dB bandwidth for modulated carrier (2 Mbps). | | 1800 | 2000 | kHz | 2 |
| P_{BW1} | 20 dB bandwidth for modulated carrier (1 Mbps). | | 950 | 1100 | kHz | 2 |
| P_{BW250} | 20 dB bandwidth for modulated carrier (250 kbps). | | 700 | 800 | kHz | 2 |
| $P_{RF1.2}$ | 1 st Adjacent Channel Transmit Power. ± 2 MHz (2 Mbps). | | | -20 | dBc | 2 |
| $P_{RF2.2}$ | 2 nd Adjacent Channel Transmit Power. ± 4 MHz (2 Mbps). | | | -45 | dBc | 2 |
| $P_{RF1.1}$ | 1 st Adjacent Channel Transmit Power. ± 1 MHz (1 Mbps). | | | -20 | dBc | 2 |
| $P_{RF2.1}$ | 2 nd Adjacent Channel Transmit Power. ± 2 MHz (1 Mbps). | | | -40 | dBc | 2 |
| $P_{RF1.250}$ | 1 st Adjacent Channel Transmit Power. ± 1 MHz (250 kbps). | | | -25 | dBc | 2 |
| $P_{RF2.250}$ | 2 nd Adjacent Channel Transmit Power. ± 2 MHz (250 kbps). | | | -40 | dBc | 2 |
| $t_{TX,30}$ | Maximum consecutive transmission time, $f_{TOL} < \pm 30$ ppm. | | | 16 | ms | 1 |
| $t_{TX,60}$ | Maximum consecutive transmission time, $f_{TOL} < \pm 60$ ppm. | | | 4 | ms | 1 |

5 Dimensions

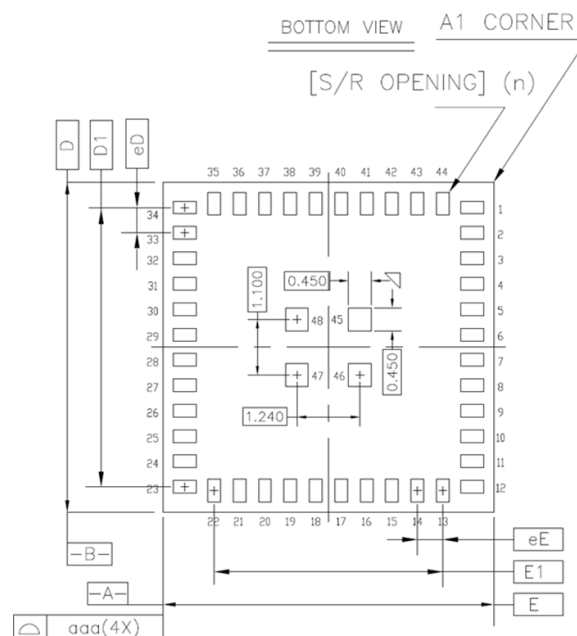
The size and thickness of the M904 module 6.5mm (W) x 6.5mm (L) x 1.3mm (H):

Top-View:

Side-View:



Bottom-View:



Dimensions

| | | Symbol | Common Dimensions |
|------------------------------|---|--------|-------------------------|
| Package : | | | PIM |
| Body Size: | X | E | 6.500 |
| | Y | D | 6.500 |
| Ball Pitch : | X | eE | 0.500 |
| | Y | eD | 0.500 |
| Total Thickness : | | A | 1.300±0.100 |
| Mold Thickness : | | M | 1.100 Ref. |
| Substrate Thickness : | | S | 0.200 Ref. |
| S/R Opening : | | | 0.450*0.450/0.250*0.450 |
| Stand Off : | | A1 | --- ~ --- |
| Ball Width : | | b | --- ~ --- |
| Package Edge Tolerance : | | aaa | 0.100 |
| Mold Flatness : | | bbb | 0.100 |
| Coplanarity: | | ddd | --- |
| Ball Offset (Package) : | | eee | --- |
| Ball Offset (Ball) : | | fff | --- |
| Ball Count : | | n | 48 |
| Edge Ball Center to Center : | X | E1 | 4.500 |
| | Y | D1 | 5.500 |

6 Pin Assignments

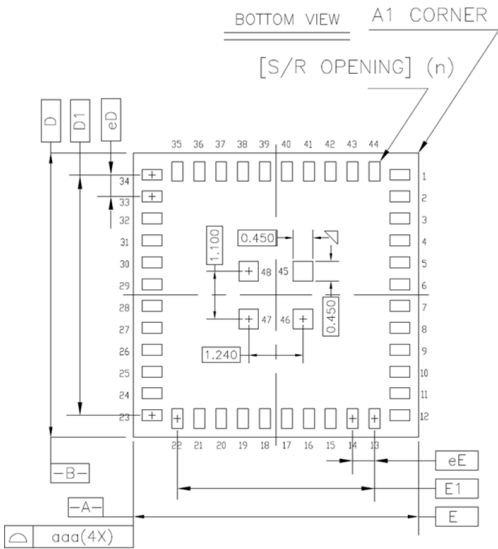
6.1 Pin Description

The foot print dimension and pin definition is defined as below

| Pin number | Pin name | Pin function | Description |
|------------|---------------|-------------------------------|---|
| 1 to 9 | VSS | Power | Ground (0V) |
| 10 | RF | BLE RF (antenna connection) | BLE RF (antenna connection) |
| 11 | ANT | Antenna | Antenna feed |
| 12 | VSS | Power | Ground (0V) |
| 13 | DEC2 | Power | Power supply decoupling |
| 14 | SWDCLK | Digital input | Hardware debug and flash programming I/O |
| 15 | SWDIO/ nRESET | Digital I/O | System reset (active low). Also hardware debug and flash programming I/O. |
| 16 | P0_16 | Digital I/O | General purpose I/O pin. |
| 17 | P0_15 | Digital I/O | General purpose I/O pin. |
| 18 | P0_14 | Digital I/O | General purpose I/O pin. |
| 19 | P0_13 | Digital I/O | General purpose I/O pin. |
| 20 | P0_09 | Digital I/O | General purpose I/O pin. |
| 21 | P0_08 | Digital I/O | General purpose I/O pin. |
| 22 | P0_06 | Digital I/O | General purpose I/O pin. |
| 23 | AIN6 | Analog input | ADC/LPCOMP input |
| 24 | AIN5 | Analog input | ADC/LPCOMP input |
| 25 | AIN4 | Analog input | ADC/LPCOMP input |
| 26 | AIN2 | Analog input | ADC/LPCOMP input |
| 27 | AIN3 | Analog input | ADC/LPCOMP input |
| 28 | AREF0 | Analog input | ADC/LPCOMP reference input |
| 29 | PWR | Power | Power supply |
| 30 | VSS | Power | Ground (0V) |
| 31 | AIN1_XL1 | Analog input Analog output | ADC/LPCOMP input Connection for 32.768 kHz crystal. |
| 32 | AIN0_XL2 | Analog input Analog input | ADC/LPCOMP input 1 Connection for 32.768 kHz crystal or external 32.768 kHz clock reference. |
| 33 | VSS | Power | Ground (0V) |
| 34 | ANT_TEST | Antenna test | Antenna open/short test |
| 35 | VSS | Power | Ground (0V) |
| 36 | AVDD | Power | Analog power supply |
| 37 to 48 | VSS | Power | Ground (0V) |

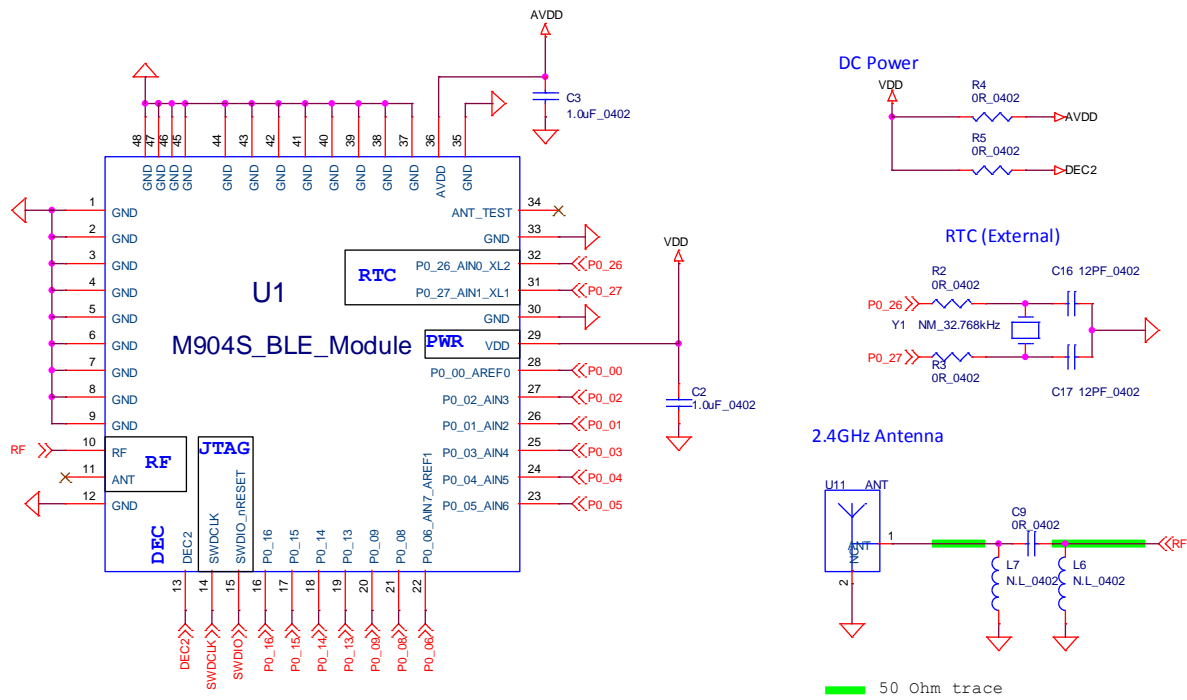
7 Recommend Footprint

Suggest on PCB: SMD (1:1)

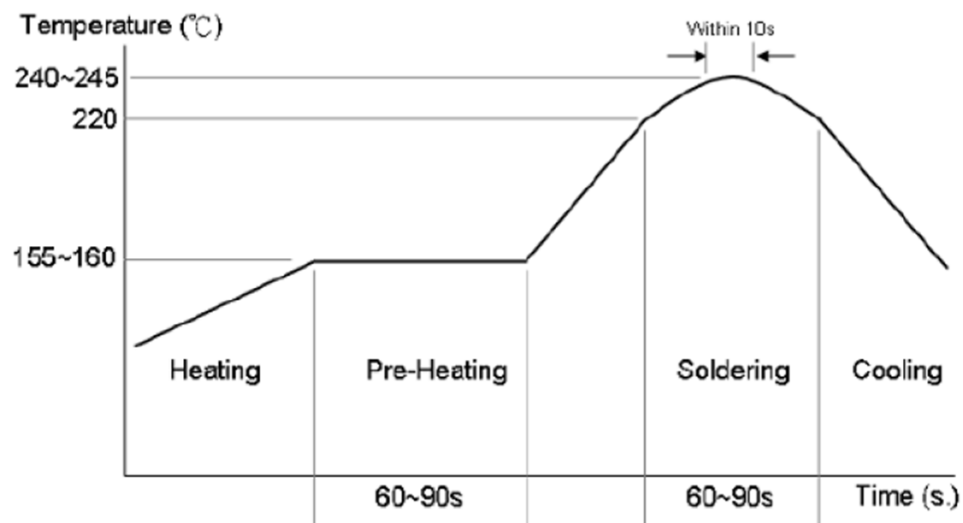


| | | Symbol | Common Dimensions |
|------------------------------|---|--------|-------------------------|
| Package : | | | PIM |
| Body Size: | X | E | 6.500 |
| | Y | D | 6.500 |
| Ball Pitch : | X | eE | 0.500 |
| | Y | eD | 0.500 |
| Total Thickness : | | A | 1.300±0.100 |
| Mold Thickness : | | M | 1.100 Ref. |
| Substrate Thickness : | | S | 0.200 Ref. |
| S/R Opening : | | | 0.450*0.450/0.250*0.450 |
| Stand Off : | | A1 | --- ~ --- |
| Ball Width : | | b | --- ~ --- |
| Package Edge Tolerance : | | aaa | 0.100 |
| Mold Flatness : | | bbb | 0.100 |
| Coplanarity: | | ddd | --- |
| Ball Offset (Package) : | | eee | --- |
| Ball Offset (Ball) : | | fff | --- |
| Ball Count : | | n | 48 |
| Edge Ball Center to Center : | X | E1 | 4.500 |
| | Y | D1 | 5.500 |

8 Reference Design Circuit



9 Recommended Reflow Profile



Profile Condition

- Suitable for Lead-Free solder
- Between 155~160°C: 60~90 sec.
- Above 220°C: 60~90 sec.
- Peak Temperature: 240~245 (<10 sec.)

10 SiP Module Preparations

10.1 Handling

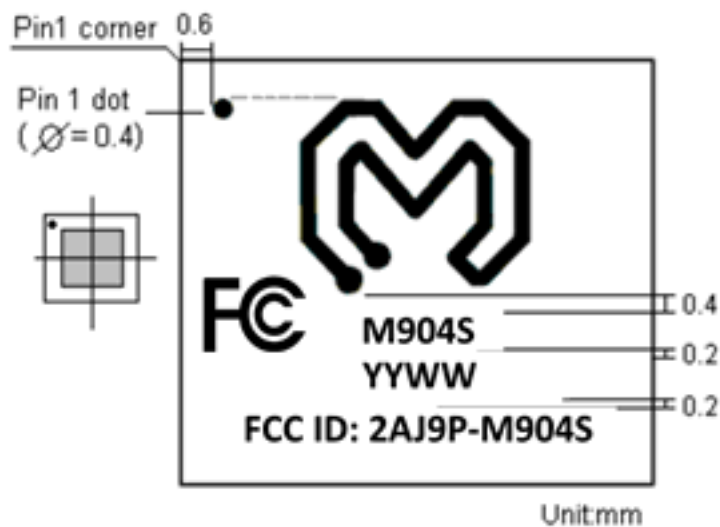
Handling the module must wear the anti-static wrist strap to avoid ESD damage. After each module is aligned and tested, it should be transport and storage with anti-static tray and packing. This protective package must be remained in suitable environment until the module is assembled and soldered onto the main board.

10.2 SMT Preparation

1. Calculated shelf life in sealed bag: 6 months at $<40^{\circ}\text{C}$ and $<90\%$ relative humidity (RH).
2. Peak package body temperature: 250°C .
3. After bag was opened, devices that will be subjected to reflow solder or other high temperature process must.
 - A. Mounted within: 72 hours of factory conditions $<30^{\circ}\text{C}/60\%$ RH.
 - B. Stored at $\leq 10\%$ RH with N2 flow box.
4. Devices require baking, before mounting, if:
 - A. Package bag does not keep in vacuumed while first time open.
 - B. Humidity Indicator Card is $>10\%$ when read at $23\pm 5^{\circ}\text{C}$.
 - C. Expose at 3A condition over 8 hours or Expose at 3B condition over 24 hours.
5. If baking is required, devices may be baked for 12 hours at $125\pm 5^{\circ}\text{C}$.

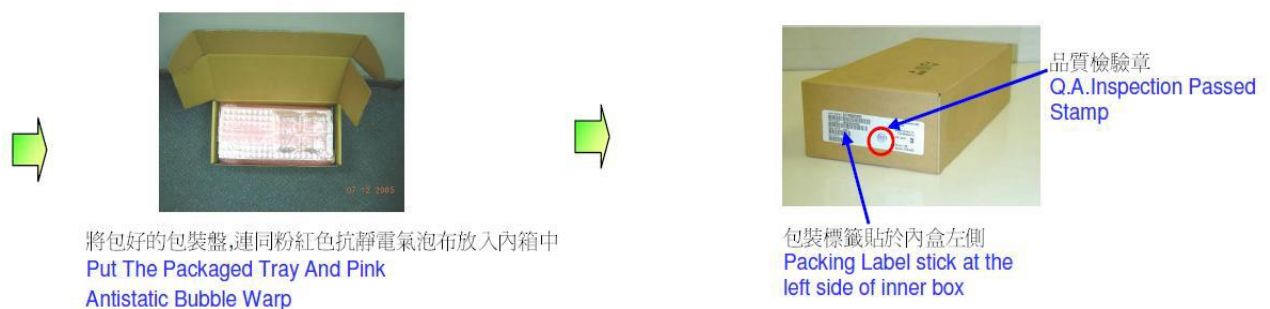
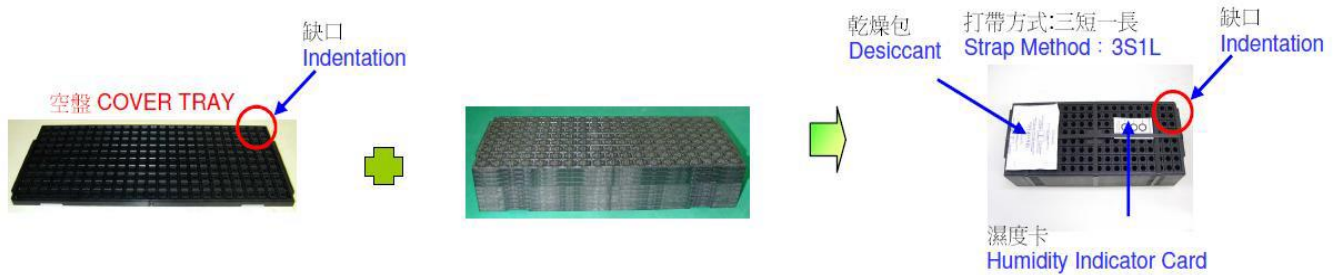
11 Package Information

11.1 Product Marking



- Line 1: M904S
- Line 2: YYWW
- Line 3: FCC ID: 2AJ9P-M904S

11.2 Package Information



12 BQB/CE/FCC Certification

12.1 FCC (USA)

Federal Communication Commission Interference Statement

This equipment has been tested and found to comply with the limits for a Class B digital device, pursuant to Part 15 of the FCC Rules. These limits are designed to provide reasonable protection against harmful interference in a residential installation. This equipment generates, uses and can radiate radio frequency energy and, if not installed and used in accordance with the instructions, may cause harmful interference to radio communications. However, there is no guarantee that interference will not occur in a particular installation. If this equipment does cause harmful interference to radio or television reception, which can be determined by turning the equipment off and on, the user is encouraged to try to correct the interference by one or more of the following measures:

- Reorient or relocate the receiving antenna.
- Increase the separation between the equipment and receiver.
- Connect the equipment into an outlet on a circuit different from that to which the receiver is connected.
- Consult the dealer or an experienced radio/TV technician for help.

FCC Caution: Any changes or modifications not expressly approved by the party responsible for compliance could void the user's authority to operate this equipment.

This device complies with Part 15 of the FCC Rules. Operation is subject to the following two conditions: (1) This device may not cause harmful interference, and (2) this device must accept any interference received, including interference that may cause undesired operation.

This device and its antenna(s) must not be co-located or operating in conjunction with any other antenna or transmitter.

IMPORTANT NOTE:

FCC Radiation Exposure Statement:

This equipment complies with FCC radiation exposure limits set forth for an uncontrolled environment. This equipment should be installed and operated with minimum distance 20cm between the radiator & your body.

IMPORTANT NOTE:

This module is intended for OEM integrator.

The OEM integrator is still responsible for the FCC compliance requirement of the end product, which integrates this module.

Appropriate measurements (e.g. 15 B compliance) and if applicable additional equipment authorizations (e.g. Verification , Doc) of the host device to be addressed by the integrator/manufacturer.

IMPORTANT NOTE:

This module is intended for OEM integrator. The OEM integrator is still responsible for the FCC compliance requirement of the end product, which integrates this module.

20cm minimum distance has to be able to be maintained between the antenna and the users for the host this module is integrated into. Under such configuration, the FCC radiation exposure limits set forth for an population/uncontrolled environment can be satisfied.

Any changes or modifications not expressly approved by the manufacturer could void the user's authority to operate this equipment.

USERS MANUAL OF THE END PRODUCT:

In the users manual of the end product, the end user has to be informed to keep at least 20cm separation with the antenna while this end product is installed and operated. The end user has to be informed that the FCC radio-frequency exposure guidelines for an uncontrolled environment can be satisfied. The end user has to also be informed that any changes or modifications not expressly approved by the manufacturer could void the user's authority to operate this equipment. If the size of the end product is smaller than the palm of the hand, then additional FCC part 15.19 statement is required to be available in the users manual: This device complies with Part 15 of FCC rules. Operation is subject to the following two conditions: (1) this device may not cause harmful interference and (2) this device must accept any interference received, including interference that may cause undesired operation.

LABEL OF THE END PRODUCT:

The final end product must be labeled in a visible area with the following " Contains TX FCC ID: **2AJ9P-M904S**". If the size of the end product is larger than the palm of the hand, then the following FCC part 15.19 statement has to also be available on the label: This device complies with Part 15 of FCC rules. Operation is subject to the following two conditions: (1) this device may not cause harmful interference and (2) this device must accept any interference received, including interference that may cause undesired operation.

Professional installation

Section 15.204(b) states that an approved "transmission system" must always be marketed as a complete system including the antenna.